



PRODUCT/PROCESS CHANGE NOTIFICATION

PCN IPD-DIS/13/7900
Dated 03 Jul 2013

**Qualification of copper wire for SOT23 and SOT323 at
ST's subcontractor in Malaysia and Design optimization
and new leadframe layout for DVIULC6-4SC6**

Table 1. Change Implementation Schedule

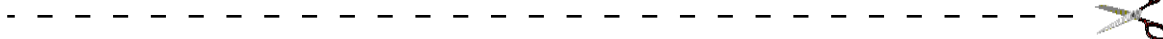
Forecasted implementation date for change	26-Jun-2013
Forecasted availability date of samples for customer	26-Jun-2013
Forecasted date for STMicroelectronics change Qualification Plan results availability	26-Jun-2013
Estimated date of changed product first shipment	02-Oct-2013

Table 2. Change Identification

Product Identification (Product Family/Commercial Product)	SOT23 and SOT323 packages
Type of change	Package assembly material change
Reason for change	to optimize our industrial process and material
Description of the change	see drawing in attached
Change Product Identification	QA number, internal codification and date code
Manufacturing Location(s)	

Table 3. List of Attachments

Customer Part numbers list	
Qualification Plan results	



Customer Acknowledgement of Receipt		PCN IPD-DIS/13/7900					
Please sign and return to STMicroelectronics Sales Office		Dated 03 Jul 2013					
<input type="checkbox"/> Qualification Plan Denied <input type="checkbox"/> Qualification Plan Approved <input type="checkbox"/> Change Denied <input type="checkbox"/> Change Approved	<table border="1" style="width: 100%; border-collapse: collapse;"> <tr><td style="padding: 2px;">Name:</td></tr> <tr><td style="padding: 2px;">Title:</td></tr> <tr><td style="padding: 2px;">Company:</td></tr> <tr><td style="padding: 2px;">Date:</td></tr> <tr><td style="padding: 2px;">Signature:</td></tr> </table>		Name:	Title:	Company:	Date:	Signature:
Name:							
Title:							
Company:							
Date:							
Signature:							
Remark							

DOCUMENT APPROVAL

Name	Function
Paris, Eric	Marketing Manager
Nopper, Christian	Product Manager
Cazaubon, Guy	Q.A. Manager

PCN Product/Process Change Notification

Change 1: Qualification of copper wire for SOT23 and SOT323 at ST's subcontractor in Malaysia

Change 2: Design optimization and new leadframe layout for DVIULC6-4SC6 and HDMIULC6-4SC6

Notification number:	IPD-DIS/13/7900	Issue Date	24/06/2013
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Issued by	Aline AUGIS
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Product series affected by the change	<p>Protection DALC208SC6 DSILC6-4SC6 DSL01xxxx DSL02xxxx DSL03xxxx DSL04xxxx DVIULC6-4SC6 ESDA25SC6-BOS ESDAxx-2SC6 ESDAxx-4BC6 ESDAxx-5SC6 ESDAxx-5W6 ESDAxxBC6 ESDAxxL ESDAxxSC5 ESDAxxSC5S ESDAxxSC6 ESDAxxW ESDAxxW5 ESDAxxW5S HDMIULC6-4SC6 LBP01-0803SC5 USBxx-2SC6 USBxx-4SC6</p> <p>IPADs EMIF01-10005W5 KBMF01SC6 USBDF01W5 USBDF02W5 USBUF01W6 USBUF02W6</p> <p>ACSwitches SMDB3</p>
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Type of change	<p>Change 1: package assembly material change</p> <p>Change 2: waferfab material change and package assembly material change</p>
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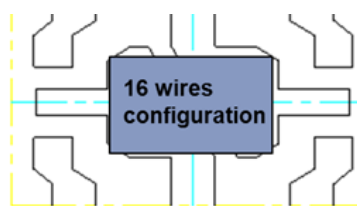
(1) IPD: Industrial & Power Discretes - ASD: Application Specific Device – IPAD™: Integrated Passive and Active Devices

Description of the change

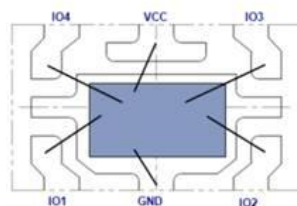
Change 1: copper wire bonding

		Before Change	After Change		
Package	Wire	Au 0.8mils, 1mils or 1.3mils	Cu 0.8mils	Package	After Change Dual pad frame Au wire
				Before Change	Single pad frame Cu wire
All SOT23-323 packages				DVIULC6-4SC6 and HDMIULC6-4SC6	

Change 2: new leadframe for DVIULC6-4SC6 and HDMIULC6-4SC6



BEFORE CHANGE



AFTER CHANGE

Reason for change

Change 1: The change is performed in order to optimize our industrial process and material.
Change 2: The design optimization and the new leadframe layout will simplify the assembly process and enable a better service to our customers.

Former versus changed product:

The changed products do not present modified electrical, dimensional or thermal parameters, leaving unchanged the current information published in the product datasheet
 The Moisture Sensitivity Level of the part (according to the IPC/JEDEC JSTD-020D standard) remains unchanged.
 The footprint recommended by ST remain the same.
 There is no change in the packing modes and the standard delivery quantities either.
 The products remain in full compliance with the ST ECOPACK®2 grade (“halogen-free”).

Disposition of former products

Deliveries of former product will continue while the conversion is brought to completion and as long as former product stocks last.

Marking and traceability

QA number, date code and internal codification

Qualification complete date

Week 16-2013

(1) IPD: Industrial & Power Discretes - ASD: Application Specific Device – IPAD™: Integrated Passive and Active Devices

Forecasted sample availability

Product family	Sub-family	Commercial part Number	Availability date
Protection	SOT23/323	DVIULC6-4SC6	From now
		ESDALC6V1W5	Week 32-2013
		HDMIULC6-4SC6	Week 28-2013
		ESDA14V2SC5	Week 28-2013
		ESDA5V3L	Week 28-2013
		ESDA6V1L	Week 28-2013
		USBLC6-2SC6	Week 28-2013
		USBLC6-4SC6	Week 28-2013
		DALC208SC6	Week 28-2013
		DSL01-008SC5	Week 28-2013
		ESDA14V2L	Week 28-2013
		ESDA25L	Week 28-2013
		ESDA5V3SC5	Week 28-2013
		ESDA5V3SC6	Week 28-2013
		ESDA6V1-4BC6	Week 28-2013
ESDA6V1SC5	Week 28-2013		
ESDA6V1W5	Week 28-2013		
ACSwitches	SOT-23	SMDB3	Week 28-2013
IPAD	SOT-323	USBUF02W6	From now

Change implementation schedule

Sales types	Estimated production start	Estimated first shipments
All	Week 36-2013	Week 40-2013

Comments:

Customer's feedback

Please contact your local ST sales representative or quality contact for requests concerning this change notification.

Absence of acknowledgement of this PCN within 30 days of receipt will constitute acceptance of the change

Absence of additional response within 90 days of receipt of this PCN will constitute acceptance of the change

Qualification program and results

QRP13126 (change 2) and QRP13127 (change 1)
 Attached

Reliability Report

*Design optimization and new leadframe layout for
DVIULC6-4SC6 and HDMIULC6-4SC6*

General Information

Product Line	<i>Transil ASD</i>
Product Description	<i>4-line ESD protection for high speed lines</i>
P/N	<i>DVIULC6-4SC6 HDMIULC6-4SC6</i>
Product Group	<i>IPD</i>
Product division	<i>ASD&IPAD</i>
Package	<i>SOT23-6L</i>
Silicon Process technology	<i>ULC</i>
Maturity level step	<i>Qualified</i>

Locations

Wafer fab	<i>STMicroelectronics Tours (France)</i>
Assembly plant	<i>Subcontractor (Malaysia)</i>
Reliability Lab	<i>STMicroelectronics Tours (France)</i>

DOCUMENT INFORMATION

Version	Date	Pages	Prepared by	Approved by	Comment
1.0	22-APRIL-2013	8	J. MICHELON	J.P. REBRASSE	PCN: IPD-DIS/13/7900

Note: This report is a summary of the reliability trials performed in good faith by STMicroelectronics in order to evaluate the potential reliability risks during the product life using a set of defined test methods.
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1 APPLICABLE AND REFERENCE DOCUMENTS

Document reference	Short description
JESD47	Stress-Test-Driven Qualification of Integrated Circuits
SOP 2614	Reliability requirements for product qualification
0061692	Reliability tests and criteria for qualifications
AEC-Q100	Stress test qualification for automotive grade integrated circuits
AEC-Q101	Stress test qualification for automotive grade discrete semiconductors

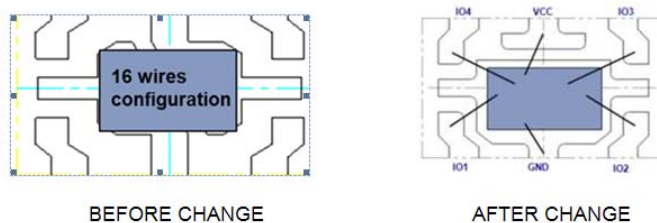
2 GLOSSARY

DUT	Device Under Test
PCB	Printed Circuit Board
SS	Sample Size

3 RELIABILITY EVALUATION OVERVIEW

3.1 Objectives

To qualify the design optimization and the new leadframe layout of DVIULC6-4SC6 and HDMIUL6-4SC6. The goal of this change will simplify the assembly process and enable a better service to our customers.



	After Change	Before Change
Package	Dual pad frame Au wire	Single pad frame Cu wire

3.2 Conclusion

Qualification plan requirements have been fulfilled without exception. Reliability tests have shown that the devices behave correctly against environmental tests (no failure). Moreover, the stability of electrical parameters during the accelerated tests demonstrates the robustness of the products and safe operation, which is consequently expected during their lifetime.

4 DEVICE CHARACTERISTICS

4.1 Device description

The **HDMIULC6-4SC6** is a monolithic, application specific discrete device dedicated to ESD protection of the HDMI connection. It also offers the same high level of protection for IEEE 1394a and IEEE 1394b/c, USB 2.0, Ethernet links, and video lines.

Its ultra high cutoff frequency (5.3 GHz) secures a high level of signal integrity. The device topology provides this integrity without compromising the complete protection of ICs against the most stringent ESD strikes.

The **DVIULC6-4SC6** is a monolithic, application specific discrete device dedicated to ESD protection of high speed interfaces, such as DVI, HDMI, IEEE 1394a, and b, USB 2.0, Ethernet links and video lines. Its ultralow line capacitance secures a high level of signal integrity without compromise in protecting sensitive chips against the most stringently characterized ESD strikes.

5 TESTS RESULTS SUMMARY

5.1 Test vehicle

Lot #	Part Number	Die Manufacturing plant	Assembly plant	Comment
1	DVIULC6-4SC6	STMicroelectronics Tours	Subcontractor Malaysia	New version: design optimization and the new leadframe layout / Cu wire
2	DVIULC6-4SC6	STMicroelectronics Tours	Subcontractor Malaysia	
3	DVIULC6-4SC6	STMicroelectronics Tours	Subcontractor Malaysia	

5.2 Test plan and results summary

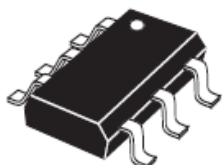
DVIULC6-4SC6

Test	PC	Std ref.	Conditions	SS	Steps	Failure/SS			Note
						Lot 1	Lot 2	Lot 3	
Die Oriented Tests									
HTRB	N	JESD22 A-108	T _j = 125°C / VR = 5V	231	168h	0/77	0/77	0/77	
					500h	0/77	0/77	0/77	
					1000h	0/77	0/77	0/77	
package Oriented Tests									
MSL1 search	Y	JESD22 A-113	T _a = 85°C / RH=85%	30	168h			0/30	MSL1 validated
THB	Y	JESD22 A-101	T _a = 85°C; RH = 85% VR = 5V	77	168h			0/77	
					500h			0/77	
					1000h			0/77	
TC	Y	JESD22 A-104	-65°C / +150°C 2 cycles / hour	77	1000 cycles			0/77	
AC	Y	JESD22 A102	T _a =121°C; 100%RH 2 BAR	77	96h			0/77	

6 ANNEXES

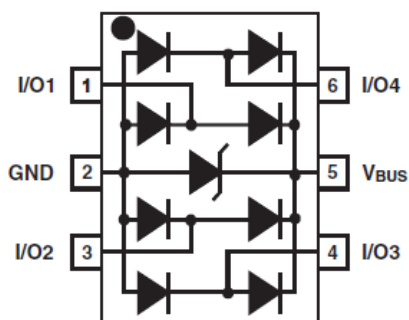
6.1 Devicedetails

Pin connection



**SOT23-6L
(JEDEC MO178AB)**

Block diagram



Package outline/Mechanical data

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	0.90	-	1.45	0.035	-	0.057
A1	0	-	0.10	0	-	0.004
A2	0.90	-	1.30	0.035	-	0.051
b	0.35	-	0.50	0.014	-	0.020
c	0.09	-	0.20	0.004	-	0.008
D	2.80	-	3.05	0.11	-	0.118
E	1.50	-	1.75	0.059	-	0.069
e	-	0.95	-	-	0.037	-
H	2.60	-	3.00	0.102	-	0.118
L	0.10	-	0.60	0.004	-	0.024
θ	0°	-	10°	0°	-	10°

6.2 Tests Description

Test name	Description	Purpose
Die Oriented		
HTRB High Temperature Reverse Bias	The device is stressed in static configuration, trying to satisfy as much as possible the following conditions: low power dissipation; max. supply voltage compatible with diffusion process and internal circuitry limitations;	To determine the effects of bias conditions and temperature on solid state devices over time. It simulates the devices operating condition in an accelerated way. To maximize the electrical field across either reverse-biased junctions or dielectric layers, in order to investigate the failure modes linked to mobile contamination, oxide ageing, layout sensitivity to surface effects.
Package Oriented		
PC Preconditioning	The device is submitted to a typical temperature profile used for surface mounting devices, after controlled moisture absorption.	As stand-alone test: to investigate the moisture sensitivity level. As preconditioning before other reliability tests: to verify that the surface mounting stress does not impact on the subsequent reliability performance. The typical failure modes are "popcorn" effect and delamination.
THB Temperature Humidity Bias	The device is biased in static configuration minimizing its internal power dissipation, and stored at controlled conditions of ambient temperature and relative humidity.	To evaluate the package moisture resistance with electrical field applied, both electrolytic and galvanic corrosion are put in evidence.
TC Temperature Cycling	The device is submitted to cycled temperature excursions, between a hot and a cold chamber in air atmosphere.	To investigate failure modes related to the thermo-mechanical stress induced by the different thermal expansion of the materials interacting in the die-package system. Typical failure modes are linked to metal displacement, dielectric cracking, molding compound delamination, wire-bonds failure, die-attach layer degradation.
AC Autoclave	The device is stored in saturated steam, at fixed and controlled conditions of pressure and temperature.	To investigate corrosion phenomena affecting die or package materials, related to chemical contamination and package hermeticity.

Reliability Report

Qualification of copper wire for SOT23 and SOT323 at ST's subcontractor in Malaysia

General Information		Locations	
Product Line	<i>Protection/IPADs/ACSwitches</i>	Wafer fab	<i>STMicroelectronics Tours (France) STMicroelectronics AngMoKio (Singapore)</i>
P/N	<u>Protection</u> DALC208SC6 DSILC6-4SC6 DSL01xxxx DSL02xxxx DSL03xxxx DSL04xxxx DVIULC6-4SC6 ESDA25SC6-BOS ESDAxx-2SC6 ESDAxx-4BC6 ESDAxx-5SC6 ESDAxx-5W6 ESDAxxBC6 ESDAxxL ESDAxxSC5 ESDAxxSC5S ESDAxxSC6 ESDAxxW ESDAxxW5 ESDAxxW5S HDMIULC6-4SC6 LBP01-0803SC5 USBxx-2SC6 USBxx-4SC6 <u>IPADs</u> EMIF01-10005W5 KBMF01SC6 USBDF01W5 USBDF02W5 USBUF01W6 USBUF02W6 <u>ACSwitches</u> SMDB3	Assembly plant	<i>Subcontractor (Malaysia)</i>
Product Group	<i>IPD</i>	Reliability Lab	<i>STMicroelectronics Tours (France)</i>
Product division	<i>ASD&IPAD</i>		
Package	<i>SOT23/323</i>		
Maturity level step	<i>Qualified</i>		

DOCUMENT INFORMATION

Version	Date	Pages	Prepared by	Approved by	Comment
1.0	22-APRIL-2013	8	J. MICHELON	J.P. REBRASSE	PCN: IPD-DIS/13/7900

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2 GLOSSARY

DUT	Device Under Test
PCB	Printed Circuit Board
SS	Sample Size

3 RELIABILITY EVALUATION OVERVIEW

3.1 Objectives

To qualify copper wire for SOT23 and SOT323 at ST's subcontractor in Malaysia.

3.2 Conclusion

Qualification plan requirements have been fulfilled without exception. Reliability tests have shown that the devices behave correctly against environmental tests (no failure). Moreover, the stability of electrical parameters during the accelerated tests demonstrates the robustness of the products and safe operation, which is consequently expected during their lifetime.

4 DEVICE CHARACTERISTICS

4.1 Change description

All SOT23-323 packages from ST's subcontractor are included in this change.

		Before Change	After Change
Package	Wire	Au 0.8mils, 1mils or 1.3mils	Cu 0.8mils

5 TESTS RESULTS SUMMARY

5.1 Test vehicle

Lot #	Part Number	Die Manufacturing plant	Assembly plant	Comments
Lot 1	ESDCAN24-2BLY	STMicroelectronics Tours (France)	Subcontractor Malaysia	Qualification Lot
Lot 2	ESDA6V1SC6	STMicroelectronics Tours (France)	Subcontractor Malaysia	Qualification Lot
Lot 3	DSL01-024SC5	STMicroelectronics Tours (France)	Subcontractor Malaysia	Qualification Lot
Lot 4	USBLC6-4SC6	STMicroelectronics AngMoKio (Singapore)	Subcontractor Malaysia	Qualification Lot

5.2 Test plan and results summary

ESDCAN24-2BLY

Test	PC	Std ref.	Conditions	SS	Steps	Failure/SS	Note
						Lot 1	
package Oriented Tests							
THB	Y	JESD22 A-101	Ta = 85°C / RH = 85% VR = 24V	77	168h	0/77	
					504h	0/77	
					1000h	0/77	
TC	Y	JESD22 A-104	[-65°C +150C] / 2 Cycles/hour	77	500C	0/77	
					1000C	0/77	
AC	Y	JESD22 A-102	Ta = 121°C / RH = 100% 2 BARS	77	96h	0/77	

ESDA6V1SC6

Test	PC	Std ref.	Conditions	SS	Steps	Failure/SS	Note
						Lot 2	
package Oriented Tests							
THB	Y	JESD22 A-101	Ta = 85°C / RH = 85% VR = 24V	77	168h	0/77	
					504h	0/77	
					1000h	0/77	
TC	Y	JESD22 A-104	[-65°C +150C] / 2 Cycles/hour	77	500C	0/77	
					1000C	0/77	
AC	Y	JESD22 A-102	Ta = 121°C / RH = 100% 2 BARS	77	96h	0/77	

DSL01-024SC5

Test	PC	Std ref.	Conditions	SS	Steps	Failure/SS	Note
						Lot 3	
package Oriented Tests							
THB	Y	JESD22 A-101	Ta = 85°C / RH = 85% VR = 24V	77	168h	0/77	
					504h	0/77	
					1000h	0/77	
TC	Y	JESD22 A-104	[-65°C +150C] / 2 Cycles/hour	77	500C	0/77	
					1000C	0/77	
AC	Y	JESD22 A-102	Ta = 121°C / RH = 100% 2 BARS	77	96h	0/77	

USBLC6-4SC6

Test	PC	Std ref.	Conditions	SS	Steps	Failure/SS	Note
						Lot 4	
Package Oriented Tests							
THB	Y	JESD22 A-101	Ta = 85°C / RH = 85% VR = 24V	77	168h	0/77	
					504h	0/77	
					1000h	0/77	
TC	Y	JESD22 A-104	[-65°C +150C] / 2 Cycles/hour	77	500C	0/77	
					1000C	0/77	
AC	Y	JESD22 A-102	Ta = 121°C / RH = 100% 2 BARS	77	96h	0/77	
HTS	N	JESD22 A-103	Ta = 150°C	77	168h	0/77	
					504h	0/77	
					1000h	0/77	
					2000h	0/77	

6 ANNEXES

6.1 Tests Description

Test name	Description	Purpose
Die Oriented		
HTRB High Temperature Reverse Bias	The device is stressed in static configuration, trying to satisfy as much as possible the following conditions: low power dissipation; max. supply voltage compatible with diffusion process and internal circuitry limitations;	To determine the effects of bias conditions and temperature on solid state devices over time. It simulates the devices operating condition in an accelerated way. To maximize the electrical field across either reverse-biased junctions or dielectric layers, in order to investigate the failure modes linked to mobile contamination, oxide ageing, layout sensitivity to surface effects.
Package Oriented		
PC Preconditioning	The device is submitted to a typical temperature profile used for surface mounting devices, after controlled moisture absorption.	As stand-alone test: to investigate the moisture sensitivity level. As preconditioning before other reliability tests: to verify that the surface mounting stress does not impact on the subsequent reliability performance. The typical failure modes are "popcorn" effect and delamination.
THB Temperature Humidity Bias	The device is biased in static configuration minimizing its internal power dissipation, and stored at controlled conditions of ambient temperature and relative humidity.	To evaluate the package moisture resistance with electrical field applied, both electrolytic and galvanic corrosion are put in evidence.
TC Temperature Cycling	The device is submitted to cycled temperature excursions, between a hot and a cold chamber in air atmosphere.	To investigate failure modes related to the thermo-mechanical stress induced by the different thermal expansion of the materials interacting in the die-package system. Typical failure modes are linked to metal displacement, dielectric cracking, molding compound delamination, wire-bonds failure, die-attach layer degradation.
AC Autoclave	The device is stored in saturated steam, at fixed and controlled conditions of pressure and temperature.	To investigate corrosion phenomena affecting die or package materials, related to chemical contamination and package hermeticity.



Public Products List

PCN Title : Qualification of copper wire for SOT23 and SOT323 at ST's subcontractor in Malaysia and Design optimization and new leadframe la
PCN Reference : IPD-DIS/13/7900
PCN Created on : 01-JUL-2013

Subject : Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change:

ST COMMERCIAL PRODUCT

DALC208SC6	DSL01-008SC5	DSL01-010SC5
DSL01-016SC5	DSL01-024SC5	DSL02-005SC5
DSL02-008SC5	DSL02-010SC5	DVIULC6-4SC6
EMIF01-10005W5	ESDA14V2L	ESDA14V2SC5
ESDA14V2SC6	ESDA17-5SC6	ESDA19SC6
ESDA25L	ESDA25SC6	ESDA25W
ESDA25W5	ESDA5V3L	ESDA5V3SC5
ESDA5V3SC6	ESDA6V1-4BC6	ESDA6V1-5SC6
ESDA6V1-5W6	ESDA6V1BC6	ESDA6V1L
ESDA6V1SC5	ESDA6V1SC6	ESDA6V1W5
ESDALC6V1W5	ESDALCL6-2SC6	HDMIULC6-4SC6
KBMF01SC6	LBP01-0803SC5	SMDB3
USBDF01W5	USBDF02W5	USBLC6-2SC6
USBLC6-4SC6	USBUF01W6	USBUF02W6
DSL03-024SC6		

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